

Session Program

Sep 26 - 30, 2011

TWEPP 2011 Topical Workshop on Electronics for Particle Physics

A5b - Packaging and Interconnects - Radiation tolerant components and systems

Vienna, Austria

Vienna University of Technology Department of Electrical
Engineering Gusshausstraße 27-29 1040 Vienna, Austria

Thu, September 29

11:00 AM

A5b - Packaging and Interconnects - Radiation tolerant components and systems

Session |

Location: Vienna, Austria, Rom El 7, **Vienna University of Technology**

Department: Institute of Microelectronics Engineering Gusshausstraße 27-29 1040 Vienna, Austria |

11:00 - 11:25 AM

SLID-ICV interconnection technology for the ATLAS pixel upgrade at SLHC

Speaker

Dr Anna Macchiolo

11:25 - 11:50 AM

Characterization of a commercial 65nm CMOS technology for SLHC applications.

Speaker

Dr Sandro Bonacini

11:50 AM - 12:15 PM

Radiation Tolerance of Readout Electronics for Belle II

Speaker

Dr Takeo Higuchi

12:15 - 12:40 PM

nanoFIP: a radiation tolerant FPGA-based WorldFIP agent

Speaker

Ms Evangelia GOUSIOU

12:40 PM